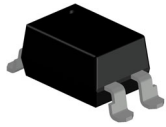


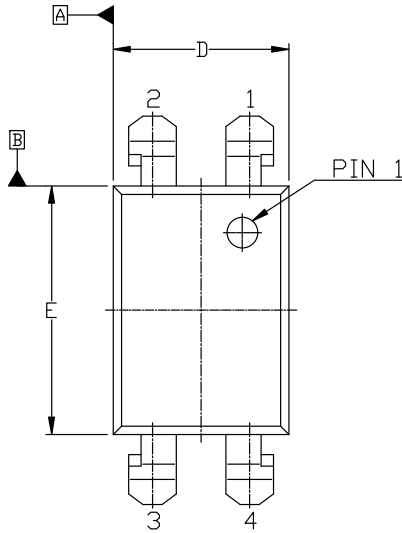
MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS



PDIP4 4.60x6.50x3.85, 2.54P
CASE 709AH
ISSUE B

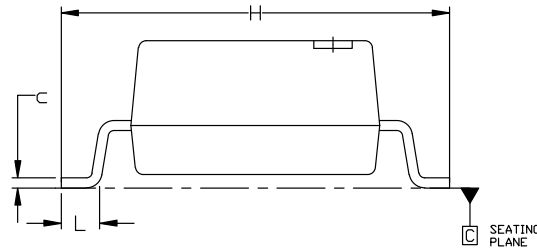
DATE 06 JUL 2023



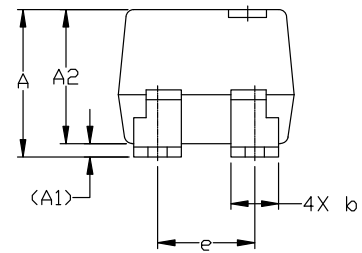
TOP VIEW

NOTES:

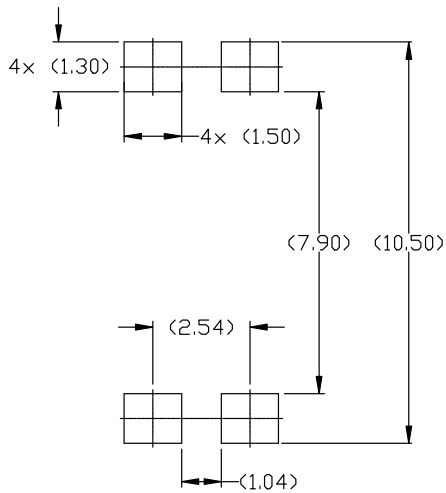
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION.
4. DRAWING FILENAME AND REVISION: MKT-N04Crev2.



END VIEW



SIDE VIEW



LAND PATTERN RECOMMENDATION

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	3.85 (TYP)		
A1	0.35 (REF)		
A2	3.00	3.50	4.00
b	1.15	1.25	1.35
c	0.26 (REF)		
D	4.10	4.60	5.10
E	6.00	6.50	7.00
e	2.29	2.54	2.79
H	9.86	10.16	10.46
L	0.75	---	1.25

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

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DESCRIPTION:	PDIP4 4.60x6.50x3.85, 2.54P	PAGE 1 OF 1

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